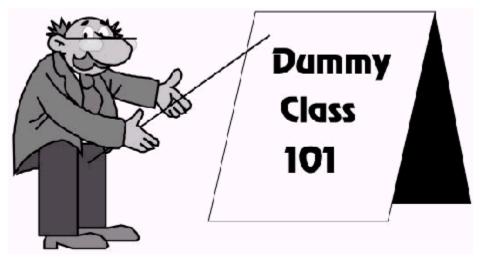
## **Quick Study Guide Dummy Components**



For more details refer to complete Dummy Class 101 available on www.topline.tv

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# TopLine 1

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# Why Dummy Components?

Save money by using TopLine Dummy Components for machine evaluation, rework practice, training, acceptance testing, demonstrations and improving SMD assembly processes.

#### Where are Dummies used?

- 1) Pick and Place Machines
- 2) Rework Practice
- 3) Training Schools
- 4) Research Laboratories
- 5) Vision Equipment
- 6) SMD Assembly Lines

#### Who needs Dummies?

- 1) Everyone whose work involves defining or refining SMD and fine-pitch assembly processes.
- 2) Everyone who demonstrates or evaluates pick and place equipment, rework or soldering machines.

### How much money is saved?

Customers often save up to 80% by using dummy components instead of "live" components.



Near by Los Angeles, California (Just 30 minutes from LAX and 10 minutes from Disneyland). Come visit us soon!

#### Stocks - Stores - Deliveries

TopLine has the world's largest inventory of Dummy Components. We ship ex-stock products the same day.

#### 7/24 Service

TopLine offers confidential access to price lists, inventory checks and logistics information 24 hours a day on our web site www.topline.tv.

### **Component Outline Drawings**

TopLine's Document Centre provides free instant access to 1000 different component outline drawings and PC board footprints on our web site 24 hours per day.



# **SMD Lead Styles**

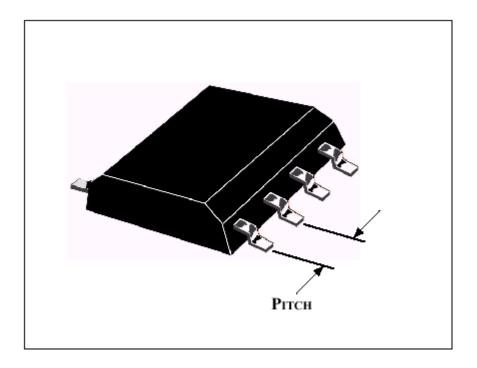
TYPE	DRAWING	COMPONENTS	
Gull-wing		SOIC QFP TSOP	
J-lead		PLCC SOJ	
Ball		BGA Chip Scale Flip Chip (Bump)	
Metalized Terminations		Capacitors Resistors Ferrites	



## **Lead Pitch**

Pitch is measured from the centre-to-centre of the leads.

Pitch is **not** the air **gap** between the leads.

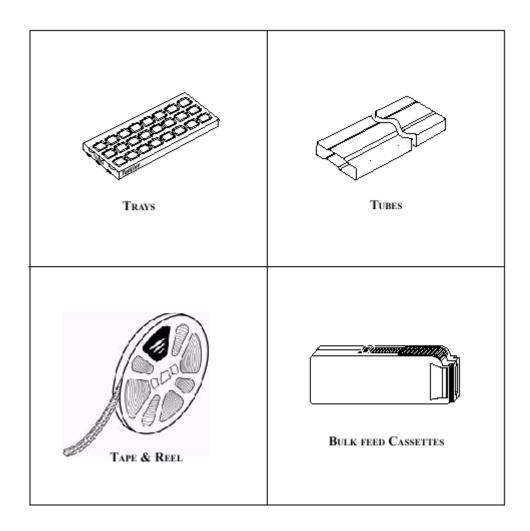


.

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# **Component Packaging**

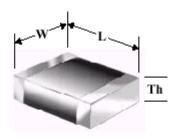
Proper **packaging** is required to **protect** the components from damage during transport. Pick and place machines require the proper feeder to "receive" the component.

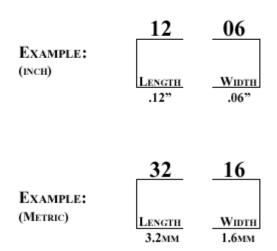


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## **Chip Size Codes**

The foot-print size of chip components are defined by a 4-digit size code. The Thickness of the component is not defined in the size code.





#### Inch versus Metric Codes

Size code of ceramic capacitors and resistors are usually stated in Inches. Tantalum capacitors are stated in metric.

SIZE CODE		Approxim	IATE SIZE
Inch	METRIC	Inch	METRIC
0402	1005	.04" x .02"	1.0 x 0.5mm
0603	1608	.06" x .03"	1.6 x 0.8mm
0805	2012	.08" x .05"	2.0 x 1.2mm
1206	3216	.12" x .06"	3.2 x 1.6mm
1210	3225	.12" x .10"	3.2 x 2.5mm
1812	4532	.18" x .12"	4.5 x 3.2mm

### All Dummies are not Created Equal

Select the <u>correct</u> Dummy to match the application.

Daisy Chains are internal connections between the leads. Daisy Chains are required to perform "Continuity" tests after the component is mounted to the PC Board. Daisy Chain "even" means that leads 1-2, 3-4, 5-6, 7-8, etc. are connected. Refer to the specific drawing for BGAs with Daisy Chains. Daisy Chain is not required for standard assembly and rework practice.



Daisy Chain

ISOLATED (-ISO) has NO internal connections between the leads. Isolated components are required for S.I.R.- Surface Insulation Resistance Testing to measure the amount of chemical residues remaining on the board after cleaning.

**-ISO** is **not** required for standard assembly and rework practice.

Dummy silicon **DIE** is attached inside dummy components when **temperature profiling** is to be performed. Die is **not** required for standard assembly and rework practice.

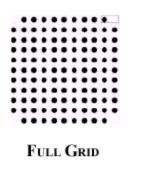
Markings (Laser or ink) may be required for specific vision equipment testing. Markings are **not** generally required for standard assembly and rework practice.

**Note:** If the customer does not specify a particular application, TopLine will supply a general-purpose dummy. Be safe - Always <u>ask</u> what the application is.



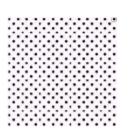
#### **BGA - Ball Grid Array**

Different ball patterns available on BGA.





PERIPHERAL





STAGGER

THERMAL VIA

### Acronyms for other "Grid Array" components:

**CBGA** - Ceramic Ball Grid Arrays.... For high temperature requirements

**fBGA** - Flex BGA ... uses a flex polyimide substrate

SBGA - Super BGA ... has metal heat spreader on top

PBGA - Plastic BGA ... Industry standard BGA

LGA - Land Grid Array ... pads without the balls

**CGA** - Column Grid Array ... solder columns instead of balls

**CSP** - Chip Scale Package ... Fine-Pitch BGA. Package is max 120% > chip size.

**uBGA** - Chip Scale Package ... trademark of Tessera

Flip Chip - Die with solder bumps ... very small.

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### QFP - Quad Flat Pack

QFP - standard Quad Flat Pack 2.0mm to 3.7mm thick

TOFP - Thin Quad Flat Pack 1.0mm thick

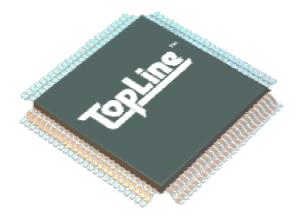
LOFP - Low Quad Flat Pack 1.4mm thick

MQFP - Metric Quad Flat Pack ... same as a standard QFP

PQFP - Plastic Quad Flat Pack ... same as a standard QFP

**BQFP** - Bumper Quad Flat Pack ... Has bumper corners

SQFP - Shrink Quad Flat Pack ... similar to QFP, but thinner



Foot Print adder to body determines tip-to-tip measurement of the leads.

**TQFP** = 2.0mm standard lead adder

**LQFP** = 2.0mm standard lead adder

QFP = 2.6mm, 3.2mm or 3.9mm standard adder

### QFP Lead Count versus Body Size

	LEAD PITCH AVAILABLE			LEAD COUNT		
POPULAR BODY SIZE	0.8мм	0.65мм	0.5мм	0.4мм	0.3мм	RANGE
7mm square	X	X	X	X		32 - 64
10mm square	X	X	X	X		44 - 80
12mm square			X			80
14mm square	X	X	X	X	X	64 - 168
14 х 20мм		X	X			100 - 128
20mm square			X			144 - 176
24mm square			X			160 - 216
28mm square			X	X		208 - 256

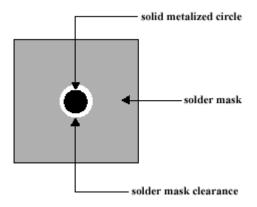
# <u>TopLine</u>™

#### PC Boards for Machine Run

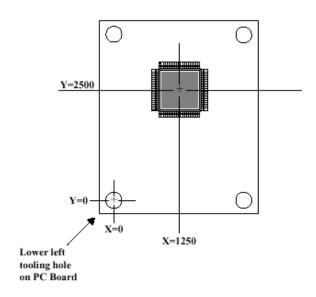
a) Fiducial Marks assist machine vision equipment to navigate precise locations on PC Boards.

There are two types of Fiducial Marks on PC Boards:

- 1) Global Fiducials are located in the far corners of the board.
- 2) Local Fiducials located at the centroid of fine-pitch components



- b) **Gerber Data** is a machine language for fabricating PC boards and making Solder Paste Stencils.
- C) Parts Placement Data tell the pick and place machine the X, Y and theta (rotation) location of the components on the PC Board.



# <u>TopLine</u>™

#### Kits for Machine and Rework

TopLine have 100 different types of kits for all skill levels from beginners to the most advanced. All kits include the PC board and enough components to assemble one side of the board.

#### Types of Kits:

- a) SMD
- b) Mixed Technology
- c) BGA
- d) Through hole
- e) Visual inspection boards

#### Machine Run Kits:

Packaging: Tape & Reel, tubes and trays. (Please specify special requirements.)

Gerber File: For making the Stencil (optional accessory)

Parts Placement: ASCII File X, Y, theta co-ordinates (optional accessory)

Fiducial marks: Included on the PC board. Tooling Holes: Included on the PC board.

#### **Hand Assembled Kits:**

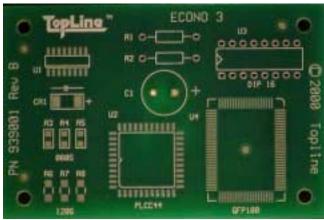
Packaging: Individually packaged or multi-pack for manual assembly. Note: Gerber File and Parts Placement Data is usually not required.

#### Other Features:

Solder mask: Green LPI is Standard.

Plating / Finish: HASL (standard) or Entek on bare copper (special order)

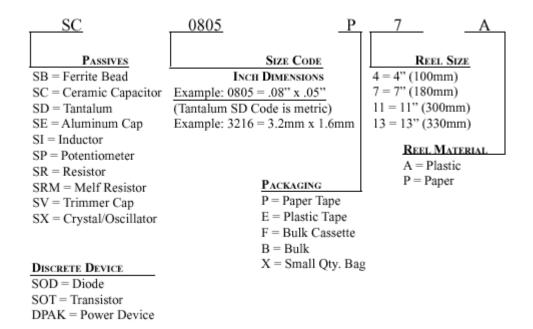
Custom boards available (requires 150 pcs minimum order)



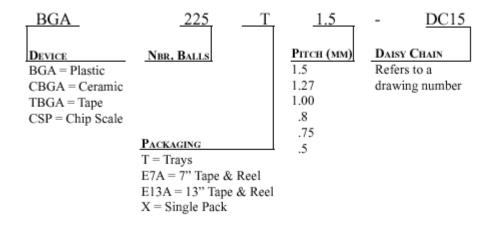
Example of mixed technology board:



### **Chip Components**



### **BGA- Ball Grid Array**





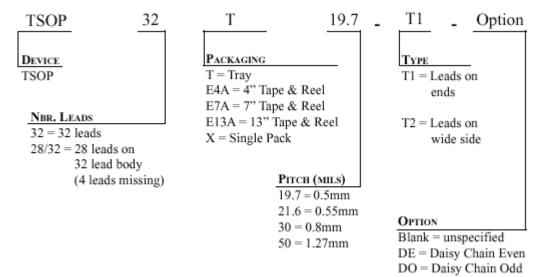
### QFP - QUAD FLAT PACK

Number Leads   FOOTPRINT   Add to body for total tip to tip dimensions.	QFP 100  Device  QFP = Quad Flat Pack  BQFP = Bumpered  LQFP = Low (1.4mm Thick)  TQFP = Thin (1.0mm Thick)  CERQUAD = Ceramic  CQFP = Ceramic (multilayer)  TAPEPAK = Molded Carrier Ring	T 25 - 3.9 - Options    Lead Pitch (MIL)   MML   MM   50   1.27   40   1.0   30   0.8   25   0.65   19.7   0.5   15.7   0.4   11.8   0.3
PACKAGING T = Tray C = Coin Stack (TAPEPAK Only) M = Tube (BQFP Only) E7A = 7" Tape & Reel E13A = 13" Tape & Reel X = Single Pack  Add to body for total tip to tip dimensions. 2.0 2.6 3.2 3.2 3.9 X = Single Pack	Number Leads	
	T = Tray C = Coin Stack (TAPEPAK Only M = Tube (BQFP Only) E7A = 7" Tape & Reel E13A = 13" Tape & Reel	Add to body for total tip to tip dimensions.  2.0 2.6 3.2
Rlank = Unenecified		OPTIONS Blank = Unspecified

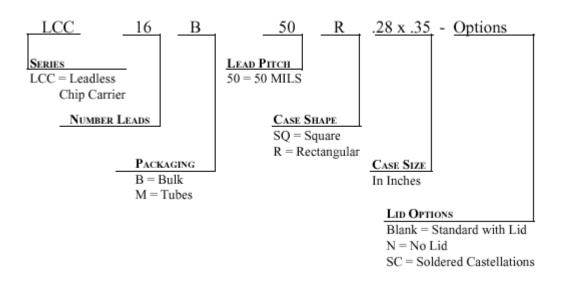
Blank = Unspecified ISO = Isolated DE = Daisy Chain Even DO = Daisy Chain Odd BUS = All leads shorted





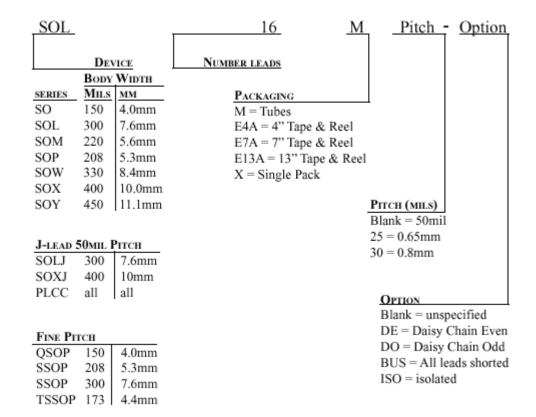


## LCC - Ceramic Leadless Chip Carrier





#### SOIC and PLCC



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